



ELECTRONIC SOLDERS

NO-CLEAN CORE SOLDER For Lead-Bearing and Lead Free Alloys

DESCRIPTION

BOW No-Clean flux is a low residue formula for use in flux-cored solder wire. Features of this flux are instant wetting action and a clear, non-corrosive residue. This flux is ideal for hand soldering and rework applications. It is formulated with a resin polymer and dendrimer activator.

FEATURES

- High activity RA formulation
- Excellent solderability for a wide variety of applications
- Classified as ROM1 per J-STD-004

AVAILABILITY

No-Clean may be obtained in a wide array of Sn/Pb and Lead Free alloys, in diameters from .009 to .125 in flux percentages from 1.1% to 3.6%, packaged on 1, 5, and 20 pound spools.

RELIABILITY PROPERTIES

Silver Chromate:	Pass
Corrosion:	Pass
Polyglycols:	None
Appearance:	Clear
Water Extract Resistivity: (ohm-cm)	32,000
Flux designation:	ROLO
Halogen Content:	Pass

STORAGE AND SHELF LIFE

Store in any dry, non-corrosive environment. Cored wire solder has a shelf life of 2 years from date of manufacture.

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